TOSHIBA MOS MEMORY PRODUCTS

1M BIT (128K WORD×8 BIT) CMOS MASK ROM SILICON GATE CMOS

TC531000AP,TC531000AF

DESCRIPTION

The TC531000AP/AF is a 1,048,576 bits read only memory organized as 131,072 words by 8 bits with a low bit cost, thus being suitable for use in program memory of microprocessor, especially character generator. The TC531000AP/AF using CMOS technology is most

suitable for low power applications where battery operation are required.

The TC531000AP/AF has one chip enable input $\overline{\text{CE}}/\text{CE}$, programmable for device selection.

FEATURES

Single 5V Power SupplyAccess Time: 150ns (Max.)

Power Dissipation

Operating Current: 40mA (Max.)
Standby Current: 20µA (Max.)
• All Inputs and Outputs: TTL Compatible

PIN CONNECTION

_				
A15 🗖	1		28	\beth $v_{ m DD}$
A12 🗖	2		27	A14
A7 🗖	3		26	A 13
A6 🗖	4		25	3A 🗖
A5 🗖	5	\hat{c}	24	□ A9
A4 🗖	6	VIEW	23	All
A3 🗖	7	H	22	A1.6
A2 🗖	8		21	A10
Al 🗖	9	(TOP	20	□ CE/CE
0A	10	I)	19	D7
DO 🗖	11		18	D6
DJ 🗖	12		17	D D5
D2 🗖	13		.16	D D4
дир □	14		15	D 3

PIN NAMES

A0 ~ A16	Address Inputs
D0 ~ D7	Data Outputs
CE/CE	Chip Enable Input
V _{DD}	Power Supply
GND	Ground

• Three State Outputs

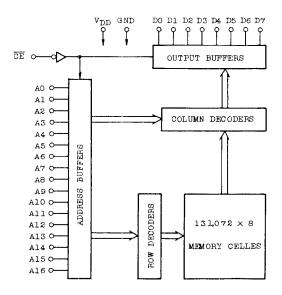
Fully Static Operation

• Programmable Chip Enable

Package

Plastic DIP: TC531000AP Plastic FP: TC531000AF

BLOCK DIAGRAM



TC531000AP,TC531000AF

MAXIMUM RATINGS

SYMBOL	ITEM	RATING	UNIT
V _{DD}	Power Supply Voltage	− 0.5 ~ 7.0	V
VIN	Input Voltage	-0.5 ~ V _{DD}	V
Vout	Output Voltage	0 ~ V _{DD}	V
PD	Power Dissipation	1.0/0.6*	W
T _{STG}	Storage Temperature	− 55 ~ 150	°C
T _{OPR}	Operating Temperature	-40 ~ 70	°C
TSOLDER	Soldering Temperature • Time	260 • 10	°C • sec

Note: * Plastic FP

D.C. OPERATING CONDITIONS $(Ta = -40 \sim 70^{\circ} C)$

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{DD}	Power Supply Voltage	4.5	5.0	5.5	V '
VIH	Input High Voltage	2.2	_	$V_{DD} + 0.3$	V
VIL	Input Low Voltage	-0.3	-	0.8	V

D.C. and OPERATING CHARACTERISTICS (Ta = $-40 \sim 70^{\circ}$ C, $V_{DD} = 5V \pm 10\%$)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
111	Input Leakage Current	VIN = 0 ~ VDD	_	±1.0	μΑ
ILO	Output Leakage Current	CE = V _{IH} , V _{OUT} = 0 ~ V _{DD}	_	±5.0	μΑ
Гон	Output High Current	V _{OH} = 2.4V	-1.0	_	mA
loL	Output Low Current	V _{OL} = 0.4V	3.2		mA
I _{DDS1}	Standby Current	CE = V _{IH}		2	mA
I _{DDS2}	Standby Current	CE = V _{DD} and V _{IN} = 0V (V _{DD})		20	μA
I _{DD01}	0 11 0	VIN = VIH /VIL , tayale = 150ns		50	mA
I _{DD02}	Operating Current	V _{IN} = V _{DD} /0V, t _{cycle} = 150ns	I	40	mA

CAPACITANCE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
CIN	Input Capacitance	f = 1MHz, Ta = 25°C	-	10	pF
Cour	Output Capacitance	f = 1MHz, Ta = 25°C	_	10	pF

Note: This parameter is periodically sampled and is not 100% tested.

A.C. CHARACTERISTICS $(V_{DD} = 5V \pm 5V \pm 10\%, Ta = -40 \sim 70^{\circ}C)$

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
tcyc	Cycle Time	150	_	ns
tACC	Access Time	_	150	ns
tce	Chip Enable Access Time	_	150	ns
tced	Output Disable Time		50	ns
tон	Output Hold Time	10	_	ns

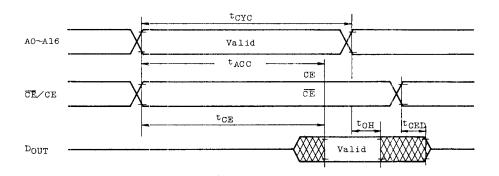
AC TEST CONDITIONS

Output Load
 Input Levels
 Timing Measurement Reference Levels
 100pF + 1TTL
 0.6V, 2.4V
 Timing Measurement Reference Levels
 Input
 0.8V, 2.2V

Output: 0.8V, 2.0V

• Input Rise and Fall Time : 5ns

TIMING WAVEFORMS



OPERATION MODE

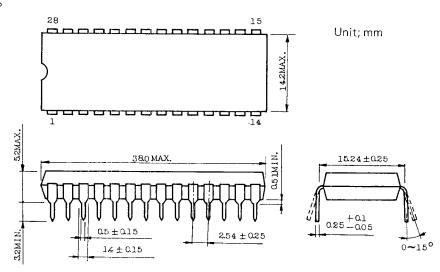
MODE	CE(CE)	A0 ~ 16	Outputs	Power
Read	L(H)	Valid	Data Out	Operating
Output Deselect	H(L)	-16-	High-Z	Standby

 $H: V_{IH}$, $L: V_{IL}$, *: V_{IH} or V_{IL}

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• OUTLINE DRAWINGS

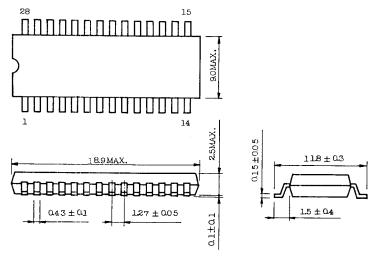
Plastic DIP



NOTE: Each lead pitch is 2.54mm.

All leads are located within 0.25mm of their true longitudinal position with respect to No. 1 and No. 28 leads.

Plastic FP



NOTE: Each lead pitch is 1.27mm.

All leads are located within 0.25mm of their true longitudinal position with respect to No. 1 and No. 28 leads.

NOTE: To shiba does not assume any responsibility for use of any circuitry described; no circuit patent licenses are implied, and To shiba reserve the right, at any time without notice, to change said circuitry. -806-